

Features

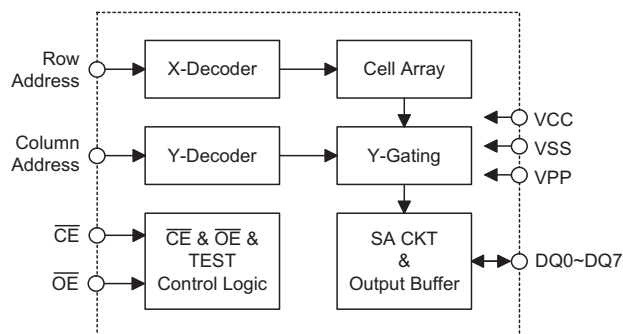
- Operating voltage: +3.3V
- Programming voltage
 - $V_{PP}=12.5V\pm0.2V$
 - $V_{CC}=6.0V\pm0.2V$
- High-reliability CMOS technology
- Latch-up immunity to 100mA from $-1.0V$ to $V_{CC}+1.0V$
- CMOS and TTL compatible I/O
- Low power consumption
 - Active: 15mA max.
 - Standby: 1 μ A typ.
- 512K×8-bits organization
- Fast read access time: 90ns
- Fast programming algorithm
- Programming time 75 μ s typ.
- Two line controls (\overline{OE} and \overline{CE})
- Standard product identification code
- Commercial temperature range (0°C to +70°C)
- 32-pin DIP/SOP/TSOP/PLCC package

General Description

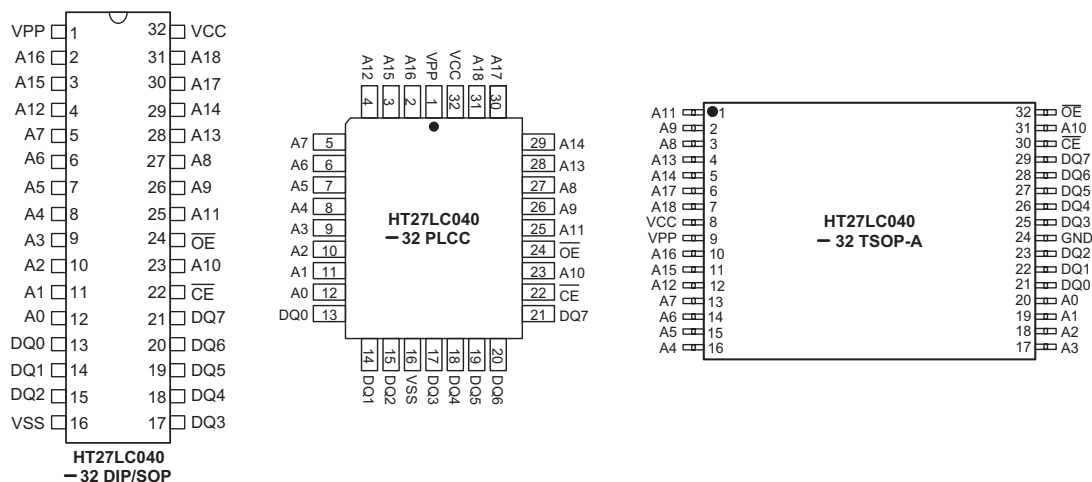
The HT27LC040 chip family is a low-power, 4096K (4,194,304) bits, +3.3V electrically one-time programmable (OTP) read-only memories (EPROM). Organized into 512K words with 8 bits per word, it features a fast single address location programming, typically at 75 μ s per byte. Any byte can be accessed in less than 90ns

with respect to Spec. This eliminates the need for WAIT states in high-performance microprocessor systems. The HT27LC040 has separate Output Enable (\overline{OE}) and Chip Enable (\overline{CE}) controls which eliminate bus contention issues.

Block Diagram



Pin Assignment



Pin Description

| Pin Name | I/O/P | Description |
|------------------------|-------|-------------------------------|
| VPP | P | Program voltage supply |
| A0~A18 | I | Address inputs |
| DQ0~DQ7 | I/O | Data inputs/outputs |
| VSS | — | Negative power supply, ground |
| $\overline{\text{CE}}$ | I | Chip enable |
| $\overline{\text{OE}}$ | I | Output enable |
| VCC | — | Positive power supply |

Absolute Maximum Rating

| | |
|---|------------------------|
| Operation Temperature Commercial | 0°C to 70°C |
| Storage Temperature | –65°C to 125°C |
| Applied VCC Voltage with Respect to VSS | –0.6V to 7.0V |
| Applied Voltage on Input Pin with Respect to VSS | –0.6V to 7.0V |
| Applied Voltage on Output Pin with Respect to VSS | –0.6V to $V_{CC}+0.5V$ |
| Applied Voltage on A9 Pin with Respect to VSS | –0.6V to 13.5V |
| Applied VPP Voltage with Respect to VSS | –0.6V to 13.5V |
| Applied READ Voltage (Functionality is guaranteed between these limits) | +3.0V to 3.6V |

Note: These are stress ratings only. Stresses exceeding the range specified under "Absolute Maximum Ratings" may cause substantial damage to the device. Functional operation of this device at other conditions beyond those listed in the specification is not implied and prolonged exposure to extreme conditions may affect device reliability.

D.C. Characteristics

| Symbol | Parameter | Test Conditions | | Min. | Typ. | Max. | Unit |
|-----------------------|--------------------------|-----------------|---|--------------------|------|----------------------|------|
| | | V _{CC} | Conditions | | | | |
| Read Operation | | | | | | | |
| V _{OH} | Output High Level | 3.3V | I _{OH} =−0.4mA | 2.4 | — | — | V |
| V _{OL} | Output Low Level | 3.3V | I _{OL} =2.1mA | — | — | 0.45 | V |
| V _{IH} | Input High Level | 3.3V | — | 2.0 | — | V _{CC} +0.5 | V |
| V _{IL} | Input Low Level | 3.3V | — | −0.3 | — | 0.8 | V |
| I _{LI} | Input Leakage Current | 3.3V | V _{IN} =0 to 3.6V | −5 | — | 5 | μA |
| I _{LO} | Output Leakage Current | 3.3V | V _{OUT} =0 to 3.6V | −10 | — | 10 | μA |
| I _{CC} | VCC Active Current | 3.3V | $\overline{CE}=V_{IL}$, f=5MHz I _{OUT} =0mA | — | — | 15 | mA |
| I _{SB1} | Standby Current (CMOS) | 3.3V | $\overline{CE}=V_{CC}\pm 0.3V$ | — | 1.0 | 10 | μA |
| I _{SB2} | Standby Current (TTL) | 3.3V | $\overline{CE}=V_{IH}$ | — | — | 0.6 | mA |
| I _{PP} | VPP Read/Standby Current | 3.3V | $\overline{CE}=\overline{OE}=V_{IL}$, V _{PP} =V _{CC} | — | — | 100 | μA |
| Programming Operation | | | | | | | |
| V _{OH} | Output High Level | 6V | I _{OH} =−0.4mA | 2.4 | — | — | V |
| V _{OL} | Output Low Level | 6V | I _{OL} =2.1mA | — | — | 0.45 | V |
| V _{IH} | Input High Level | 6V | — | 0.7V _{CC} | — | V _{CC} +0.5 | V |
| V _{IL} | Input Low Level | 6V | — | −0.5 | — | 0.8 | V |
| I _{LI} | Input Load Current | 6V | V _{IN} =V _{IL} , V _{IH} | — | — | 5.0 | μA |
| V _H | A9 Product ID Voltage | 6V | — | 11.5 | — | 12.5 | V |
| I _{CC} | VCC Supply Current | 6V | — | — | — | 40 | mA |
| I _{PP} | VPP Supply Current | 6V | $\overline{CE}=V_{IL}$ | — | — | 10 | mA |
| Capacitance | | | | | | | |
| C _{IN} | Input Capacitance | 5V | V _{IN} =0V | — | 8 | 12 | pF |
| C _{OUT} | Output Capacitance | 5V | V _{OUT} =0V | — | 8 | 12 | pF |
| C _{VPP} | VPP Capacitance | 5V | V _{PP} =0V | — | 18 | 25 | pF |

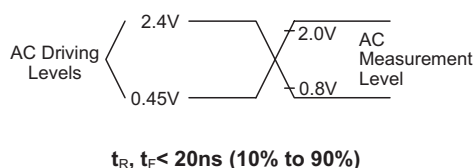
A.C. Characteristics

Ta=+25°C±5°C

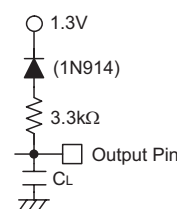
| Symbol | Parameter | Test Conditions | | Min. | Typ. | Max. | Unit |
|------------------|---|-----------------|--------------------------------------|------|------|------|------|
| | | V _{CC} | Conditions | | | | |
| Read Operation | | | | | | | |
| t _{ACC} | Address to Output Delay | 3.3V | $\overline{CE}=\overline{OE}=V_{IL}$ | — | — | 90 | ns |
| t _{CE} | Chip Enable to Output Delay | 3.3V | $\overline{OE}=V_{IL}$ | — | — | 90 | ns |
| t _{OE} | Output Enable to Output Delay | 3.3V | $\overline{CE}=V_{IL}$ | — | — | 45 | ns |
| t _{DF} | \overline{CE} or \overline{OE} High to Output Float, Whichever Occurred First | 3.3V | — | — | — | 40 | ns |
| t _{OH} | Output Hold from Address, \overline{CE} or \overline{OE} , Whichever Occurred First | 3.3V | — | 0 | — | — | ns |

| Symbol | Parameter | Test Conditions | | Min. | Typ. | Max. | Unit |
|-----------------------|--|-----------------|------------|------|------|------|------|
| | | V _{CC} | Conditions | | | | |
| Programming Operation | | | | | | | |
| t _{AS} | Address Setup Time | 6V | — | 2 | — | — | μs |
| t _{OES} | $\overline{\text{OE}}$ Setup Time | 6V | — | 2 | — | — | μs |
| t _{DS} | Data Setup Time | 6V | — | 2 | — | — | μs |
| t _{AH} | Address Hold Time | 6V | — | 0 | — | — | μs |
| t _{DH} | Data Hold Time | 6V | — | 2 | — | — | μs |
| t _{DFP} | Output Enable to Output Float Delay | 6V | — | 0 | — | 130 | ns |
| t _{VPS} | V _{PP} Setup Time | 6V | — | 2 | — | — | μs |
| t _{PW} | $\overline{\text{CE}}$ Program Pulse Width | 6V | — | 30 | 75 | 105 | μs |
| t _{VCS} | V _{CC} Setup Time | 6V | — | 2 | — | — | μs |
| t _{CES} | $\overline{\text{CE}}$ Setup Time | 6V | — | 2 | — | — | μs |
| t _{OE} | Data Valid from $\overline{\text{OE}}$ | 6V | — | — | — | 150 | ns |
| t _{PRT} | V _{PP} Pulse Rise Time During Programming | 6V | — | 2 | — | — | μs |

Test Waveforms and Measurements



Output Test Load



Note: C_L=100pF including jig capacitance

Functional Description

Programming of the HT27LC040

When the HT27LC040 is delivered, the chip has all 4096K bits in the "ONE", or HIGH state. "ZEROS" are loaded into the HT27LC040 through programming.

The programming mode is entered when $12.5 \pm 0.2\text{V}$ is applied to the V_{PP} pin, $\overline{\text{OE}}$ is at V_{IH}, and $\overline{\text{CE}}$ is V_{IL}. For programming, the data to be programmed is applied with 8 bits in parallel to the data pins.

The programming flowchart in Figure 3 shows the fast interactive programming algorithm. The interactive algorithm reduces programming time by using 30μs to 105μs programming pulses and giving each address only as many pulses as is necessary in order to reliably program the data. After each pulse is applied to a given address, the data in that address is verified. If the data is not verified, additional pulses are given until it is verified or until the maximum number of pulses is reached while sequencing through each address of the HT27LC040. This process is repeated while sequencing through each address of the HT27LC040. This part

of the programming algorithm is done at V_{CC}=6.0V to assure that each EPROM bit is programmed to a sufficiently high threshold voltage. This ensures that all bits have sufficient margin. After the final address is completed, the entire EPROM memory is read at V_{CC}=V_{PP}=3.3±0.3V to verify the entire memory.

Program Inhibit Mode

Programming of multiple HT27LC040 in parallel with different data is also easily accomplished by using the Program Inhibit Mode. Except for $\overline{\text{CE}}$, all like inputs of the parallel HT27LC040 may be common. A TTL low-level program pulse applied to an HT27LC040 $\overline{\text{CE}}$ input with V_{PP}=12.5±2V, and $\overline{\text{OE}}$ HIGH will program that HT27LC040. A high-level $\overline{\text{CE}}$ input inhibits the HT27LC040 from being programmed.

Program Verify Mode

Verification should be performed on the programmed bits to determine whether they were correctly programmed. The verification should be performed with \overline{OE} at V_{IL} , and \overline{CE} at V_{IH} , and VPP at its programming voltage.

Auto Product Identification

The Auto Product Identification mode allows the reading out of a binary code from an EPROM that will identify its manufacturer and the type. This mode is intended for programming to automatically match the device to be programmed with its corresponding programming algorithm. This mode is functional in the $25^{\circ}\text{C} \pm 5^{\circ}\text{C}$ ambient temperature range that is required when programming the HT27LC040.

To activate this mode, the programming equipment must force $12.0 \pm 0.5\text{V}$ on the address line A9 of the HT27LC040. Two identifier bytes may then be sequenced from the device outputs by toggling address line A0 from V_{IL} to V_{IH} , when $A1 = V_{IH}$. All other address lines must be held at V_{IH} during Auto Product Identification mode.

Byte 0 ($A0 = V_{IL}$) represents the manufacturer code, and byte 1 ($A0 = V_{IH}$), the device code. For HT27LC040, these two identifier bytes are given in the Operation mode truth table. When $A1 = V_{IL}$, the HT27LC040 will read out the binary code of 7F, continuation code, to signify the unavailability of manufacturer ID codes.

Read Mode

The has two control functions, both of which must be logically satisfied in order to obtain data at outputs. Chip Enable (\overline{CE}) is the power control and should be used for device selection. Output Enable (\overline{OE}) is the output control and should be used to gate data to the output pins, independent of device selection. Assuming that addresses are stable, address access time (t_{ACC}) is equal to the delay from \overline{CE} to output (t_{CE}). Data is available at the outputs (t_{OE}) after the falling edge of \overline{OE} , assuming the \overline{CE} has been LOW and addresses have been stable for at least $t_{ACC} - t_{OE}$.

Standby Mode

The HT27LC040 has CMOS standby mode which reduces the maximum VCC current to $10\mu\text{A}$. It is placed in CMOS standby when \overline{CE} is at $V_{CC} \pm 0.3\text{V}$. The HT27LC040 also has a TTL-standby mode which reduces the maximum VCC current to 0.6mA . It is placed in TTL-standby when \overline{CE} is at V_{IH} . When in standby mode, the outputs are in a high-impedance state, independent of the \overline{OE} input.

Two-line Output Control Function

To accommodate multiple memory connections, a two-line control function is provided to allow for:

- Low memory power dissipation
- Assurance that output bus contention will not occur

It is recommended that \overline{CE} be decoded and used as the primary device-selection function, while \overline{OE} be made a common connection to the READ line from the system control bus. This assures that all deselected memory devices are in their low-power standby mode and that the output pins are only active when data is desired from a particular memory device.

System Considerations

During the switch between active and standby conditions, transient current peaks are produced on the rising and falling edges of Chip Enable. The magnitude of these transient current peaks is dependent on the output capacitance loading of the device. At a minimum, a $0.1\mu\text{F}$ ceramic capacitor (high frequency, low inherent inductance) should be used on each device between VCC and VPP to minimize transient effects. In addition, to overcome the voltage drop caused by the inductive effects of the printed circuit board traces on EPROM arrays, a $4.7\mu\text{F}$ bulk electrolytic capacitor should be used between VCC and VPP for each eight devices. The location of the capacitor should be close to where the power supply is connected to the array.

Operation Mode Truth Table

All the operation modes are shown in the table following.

| Mode | \overline{CE} | \overline{OE} | A0 | A1 | A9 | VPP | Output |
|-----------------------|------------------------|-----------------|-----------------|-----------------|--------------------|-----------------|------------------|
| Read | V _{IL} | V _{IL} | X | X | X | V _{CC} | Dout |
| Output Disable | V _{IL} | V _{IH} | X | X | X | V _{CC} | High Z |
| Standby (TTL) | V _{IH} | X | X | X | X | V _{CC} | High Z |
| Standby (CMOS) | V _{CC} ± 0.3V | X | X | X | X | V _{CC} | High Z |
| Program | V _{IL} | V _{IH} | X | X | X | V _{PP} | D _{IN} |
| Program Verify | X | V _{IL} | X | X | X | V _{PP} | D _{OUT} |
| Product Inhibit | V _{IH} | X | X | X | X | V _{PP} | High Z |
| Manufacturer Code (3) | V _{IL} | V _{IL} | V _{IL} | V _{IH} | V _H (1) | V _{CC} | 1C |
| Device Type Code (3) | V _{IL} | V _{IL} | V _{IH} | V _{IH} | V _H (1) | V _{CC} | 04 |

Note: (1) V_H = 12.0V ± 0.5V

(2) X=Either V_{IH} or V_{IL}

(3) For Manufacturer Code and Device Code, A1=V_{IH}, When A1=V_{IL}, both codes will read 7F

Product Identification Code

| Code | Pins | | | | | | | | | | Hex Data |
|--------------|------|----|-----|-----|-----|-----|-----|-----|-----|-----|----------|
| | A0 | A1 | DQ7 | DQ6 | DQ5 | DQ4 | DQ3 | DQ2 | DQ1 | DQ0 | |
| Manufacturer | 0 | 1 | 0 | 0 | 0 | 1 | 1 | 1 | 0 | 0 | 1C |
| Device Type | 1 | 1 | 0 | 0 | 0 | 0 | 0 | 1 | 0 | 0 | 04 |
| Continuation | 0 | 0 | 0 | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 7F |
| | 1 | 0 | 0 | 1 | 1 | 1 | 1 | 1 | 1 | 1 | 7F |

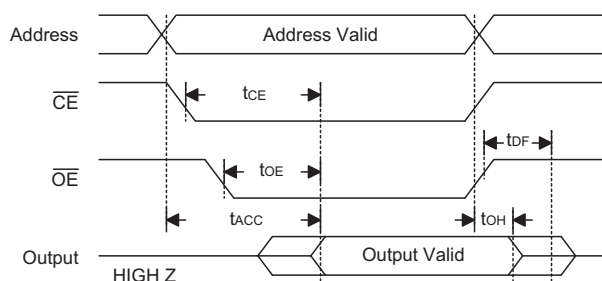


Figure 1. A.C. Waveforms for Read Operation

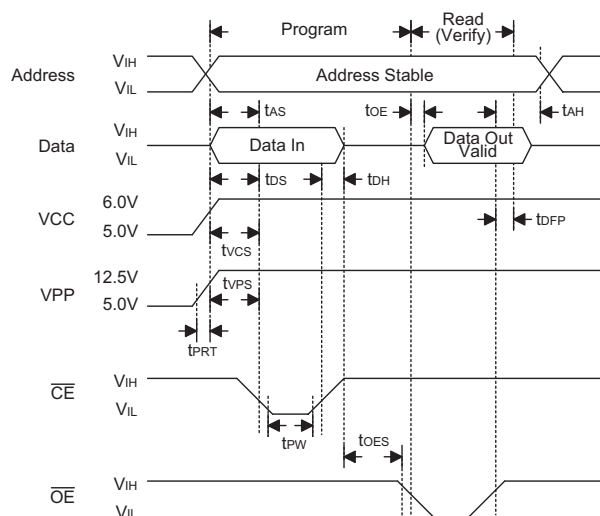
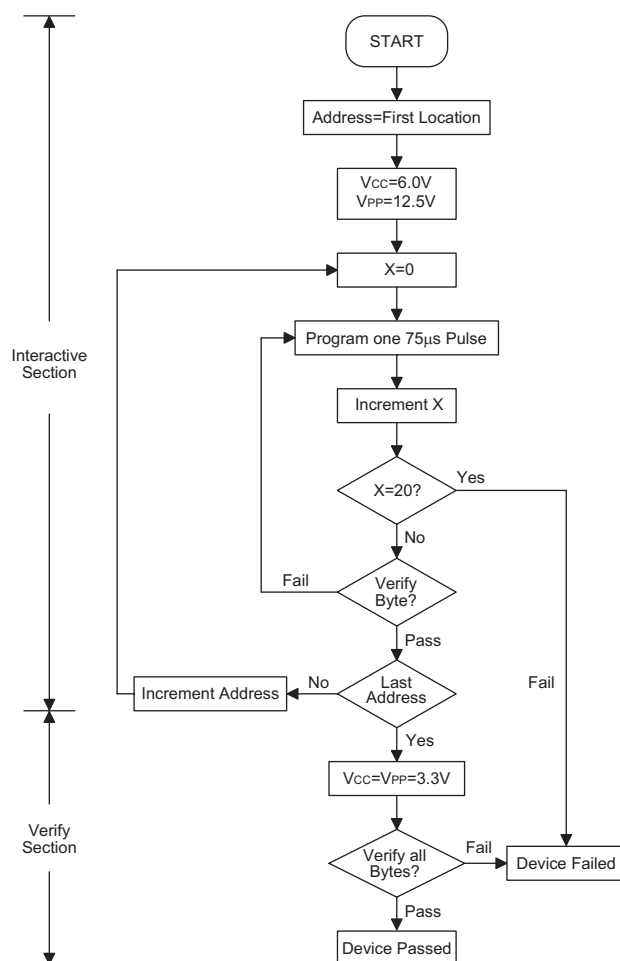
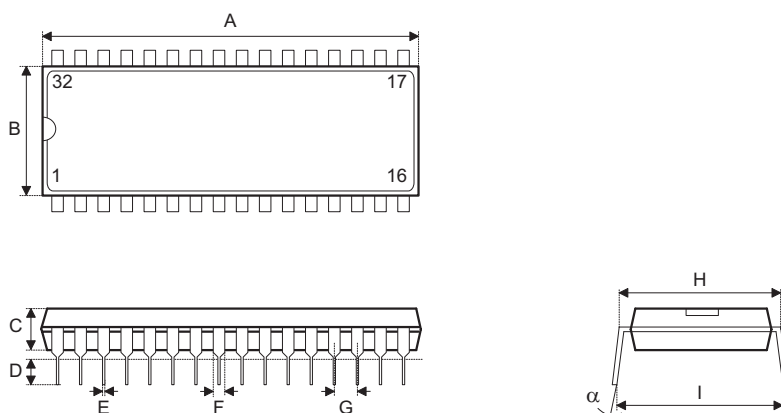


Figure 2. Programming Waveforms

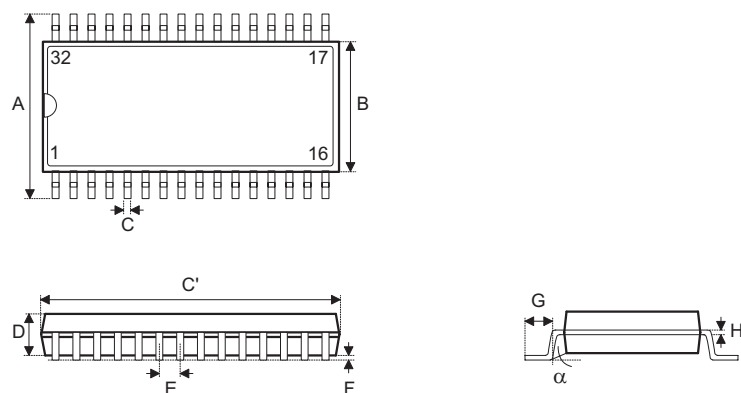


Note: Either 105µs or 30µs pulse.

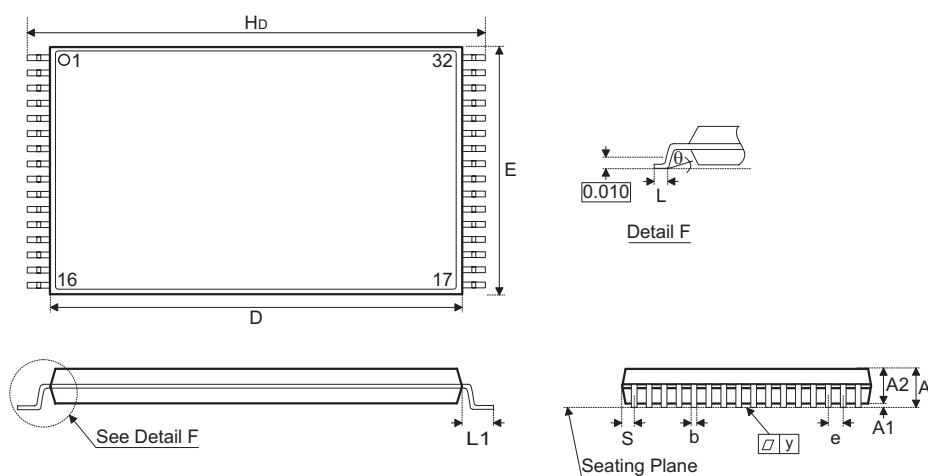
Figure 3. Fast Programming Flowchart

Package Information
32-pin DIP (600mil) Outline Dimensions


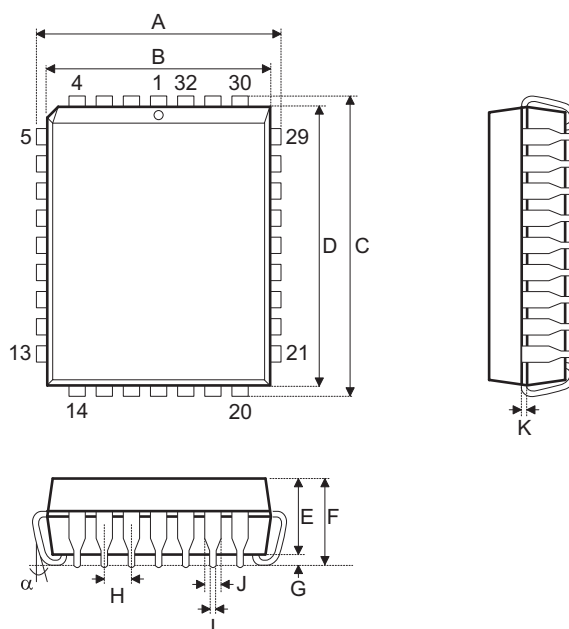
| Symbol | Dimensions in mil | | |
|----------|-------------------|------|------|
| | Min. | Nom. | Max. |
| A | 1635 | — | 1665 |
| B | 535 | — | 555 |
| C | 145 | — | 155 |
| D | 125 | — | 145 |
| E | 16 | — | 20 |
| F | 50 | — | 70 |
| G | — | 100 | — |
| H | 595 | — | 615 |
| I | 635 | — | 670 |
| α | 0° | — | 15° |

32-pin SOP (450mil) Outline Dimensions


| Symbol | Dimensions in mil | | |
|----------|-------------------|------|------|
| | Min. | Nom. | Max. |
| A | 543 | — | 557 |
| B | 440 | — | 450 |
| C | 14 | — | 20 |
| C' | — | — | 817 |
| D | 100 | — | 112 |
| E | — | 50 | — |
| F | 4 | — | — |
| G | 32 | — | 38 |
| H | 4 | — | 12 |
| α | 0° | — | 10° |

32-pin TSOP (8×20) Outline Dimensions


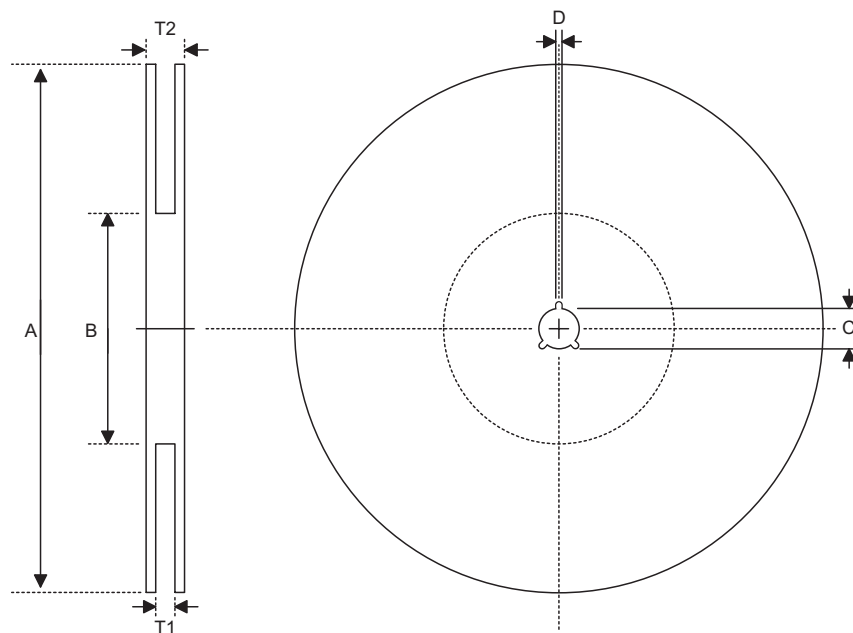
| Symbol | Dimensions in mm | | |
|----------|------------------|------|-------|
| | Min. | Nom. | Max. |
| A | — | — | 1.20 |
| A1 | 0.05 | — | 0.15 |
| A2 | 0.95 | — | 1.05 |
| b | — | 0.22 | — |
| D | 18.30 | — | 18.50 |
| H_D | 19.80 | — | 20.20 |
| E | 7.90 | — | 8.10 |
| e | — | 0.50 | — |
| L | — | 0.60 | — |
| L1 | — | 0.80 | — |
| θ | 0° | — | 5° |

32-pin PLCC Outline Dimensions


| Symbol | Dimensions in mil | | |
|----------|-------------------|------|------|
| | Min. | Nom. | Max. |
| A | 485 | — | 495 |
| B | 445 | — | 455 |
| C | 585 | — | 595 |
| D | 545 | — | 555 |
| E | 105 | — | 115 |
| F | — | — | 140 |
| G | 15 | — | — |
| H | — | 50 | — |
| I | 16 | — | 22 |
| J | 24 | — | 32 |
| K | 8 | — | 12 |
| α | 0° | — | 10° |

Product Tape and Reel Specifications

Reel Dimensions

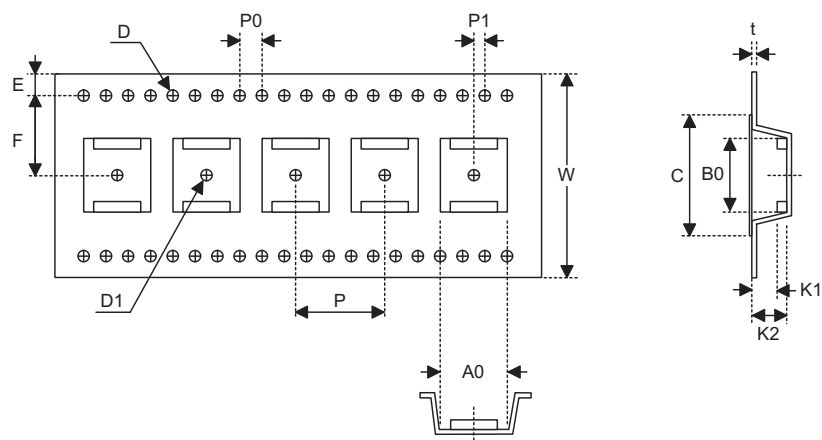


SOP 32W

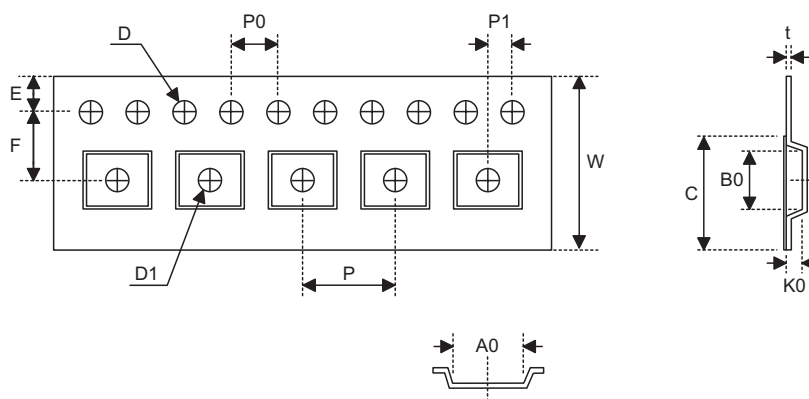
| Symbol | Description | Dimensions in mm |
|--------|-----------------------|------------------|
| A | Reel Outer Diameter | 330±1.0 |
| B | Reel Inner Diameter | 100±0.1 |
| C | Spindle Hole Diameter | 13.0+0.5 -0.2 |
| D | Key Slit Width | 2.0±0.5 |
| T1 | Space Between Flange | 32.8+0.3 -0.2 |
| T2 | Reel Thickness | 38.2±0.2 |

PLCC 32

| Symbol | Description | Dimensions in mm |
|--------|-----------------------|------------------|
| A | Reel Outer Diameter | 330±1.0 |
| B | Reel Inner Diameter | 62±1.5 |
| C | Spindle Hole Diameter | 13.0+0.5 -0.2 |
| D | Key Slit Width | 2.0±0.5 |
| T1 | Space Between Flange | 24.8+0.3 -0.2 |
| T2 | Reel Thickness | 30.2±0.2 |

Carrier Tape Dimensions

SOP 32W

| Symbol | Description | Dimensions in mm |
|--------|--|------------------|
| W | Carrier Tape Width | 32.0+0.3 -0.1 |
| P | Cavity Pitch | 16.0±0.1 |
| E | Perforation Position | 1.75±0.1 |
| F | Cavity to Perforation (Width Direction) | 14.2±0.1 |
| D | Perforation Diameter | 1.55±0.1 |
| D1 | Cavity Hole Diameter | 2.0+0.25 |
| P0 | Perforation Pitch | 4.0±0.1 |
| P1 | Cavity to Perforation (Length Direction) | 2.0±0.1 |
| A0 | Cavity Length | 14.7±0.1 |
| B0 | Cavity Width | 20.9±0.1 |
| K1 | Cavity Depth | 3.0±0.1 |
| K2 | Cavity Depth | 3.4±0.1 |
| t | Carrier Tape Thickness | 0.35±0.05 |
| C | Cover Tape Width | 25.5 |



PLCC 32

| Symbol | Description | Dimensions in mm |
|--------|--|-------------------|
| W | Carrier Tape Width | 24.0±0.3 |
| P | Cavity Pitch | 18.0±0.1 |
| E | Perforation Position | 1.75±0.1 |
| F | Cavity to Perforation (Width Direction) | 11.5±0.1 |
| D | Perforation Diameter | 1.5+0.1 |
| D1 | Cavity Hole Diameter | 1.55+1.0 -0.05 |
| P0 | Perforation Pitch | 4.0±0.1 |
| P1 | Cavity to Perforation (Length Direction) | 2.0±0.1 |
| A0 | Cavity Length | 13.1±0.1 |
| B0 | Cavity Width | 15.5±0.1 |
| K0 | Cavity Depth | 3.9±0.1 |
| t | Carrier Tape Thickness | 0.30±0.05 |
| C | Cover Tape Width | 21.3 |

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